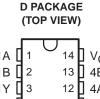
- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree†

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 7.5 ns at 5 V



	_	. ,	L
1A		14] V _{CC}] 4B
1B	2	13] 4B
1Y	[]3	12] 4A
2A	[]4	11] 4Y
2B	[] 5	10] 3B
2Y		9] 3A
GND	[]7	8] 3Y
			1

description/ordering information

The SN74AC32 is a quadruple 2-input positive-OR gate. The device performs the Boolean function Y = A + B or $Y = A \bullet B$ in positive logic.

ORDERING INFORMATION

TA	PACKAGE	±	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SOIC - D	Tape and reel	SN74AC32MDREP	SAC32MEP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Χ	Н
X	Н	Н
L	L	L

logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±200 mA
Package thermal impedance, θ _{JA} (see Note 2)	86°C/W
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2	6	V	
		V _{CC} = 3 V	2.1			
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15		V	
		V _{CC} = 5.5 V	3.85			
		V _{CC} = 3 V		0.9		
VIL	Low-level input voltage	V _{CC} = 4.5 V		1.35	V	
		V _{CC} = 5.5 V		1.65		
٧ı	Input voltage			VCC	V	
VO	Output voltage		0	VCC	V	
		V _{CC} = 3 V		-12		
lOH	High-level output current	V _{CC} = 4.5 V		-24	mA	
		V _{CC} = 5.5 V		-24		
		V _{CC} = 3 V		12		
loL	Low-level output current	V _{CC} = 4.5 V		24	mA	
		V _{CC} = 5.5 V		24		
Δt/Δν	Input transition rise or fall rate			8	ns/V	
TA	Operating free-air temperature		-55	125	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752	TEGT COURTIONS	.,	T,	Δ = 25°C	;		BAAV				
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT			
		3 V	2.9			2.9					
	I _{OH} = -50 μA	4.5 V	4.4			4.4					
V		5.5 V	5.4			5.4		V			
VOH	I _{OH} = - 12 mA	3 V	2.56			2.4		V			
	044	4.5 V	3.86			3.7					
	I _{OH} = – 24 mA	5.5 V	4.86			4.7					
		3 V		0.002	0.1		0.1	V			
	$I_{OL} = 50 \mu A$	4.5 V		0.001	0.1		0.1				
.,		5.5 V		0.001	0.1		0.1				
VOL	I _{OL} = 12 mA	3 V			0.36		0.5				
		4.5 V			0.36		0.5				
	I _{OL} = 24 mA	5.5 V			0.36		0.5				
I _I A or B ports	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ			
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40	μΑ			
Ci	V _I = V _{CC} or GND	5 V		2.6				pF			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V $\,\pm\,$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	Վ = 25°C	;	BAINI	BAAV	LINUT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	V	1.5	7	9	1	12	20
t _{PHL}	AUID	I	1.5	7	8.5	1	11.5	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\,\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

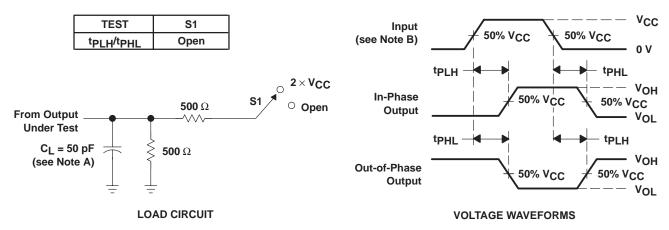
PARAMETER	FROM	то	T,	չ = 25°C	;	MAINI	MAY	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	V	1.5	5.5	7.5	1	9	20
t _{PHL}	AUIB	ſ	1.5	5	7	1	8.5	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	$C_L = 50 pF$,	f = 1 MHz	40	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AC32MDREP	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SAC32MEP	Samples
V62/04616-01XE	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SAC32MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74AC32-EP:

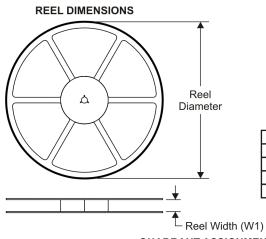
• Military: SN54AC32

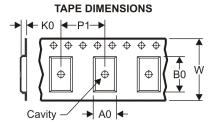
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



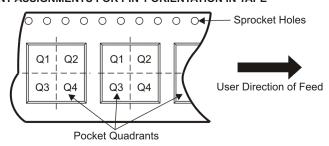
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

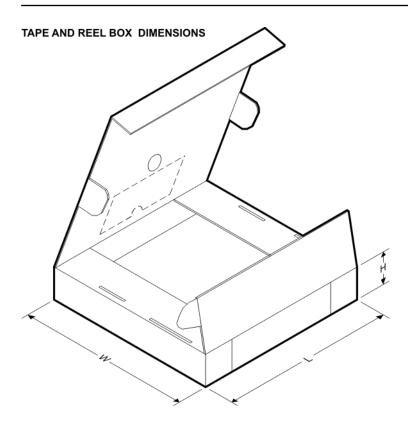
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC32MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1





*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74AC32MDREP	SOIC	D	14	2500	333.2	345.9	28.6

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